

IN THE SPECIFICATION

Please replace paragraph 34 with the following rewritten paragraph:

The pumping baffle 40 slides along the center line of the wafer chuck assembly/ lower electrode 41 in the axial direction through the force exerted by a plurality of lift pin assemblies 26. Each lift pin assembly 26 can act in unison thereby lifting the entire pumping baffle 40. Also, each lift pin assembly 26 can act individually, lifting only one side of the pumping baffle 40 at a time or lifting its respective section thereby causing a tilt in the pumping baffle 40. The adjusting of the pumping baffle 40 (i.e., changes in the tilt or elevation) causes changes in the fluid flow and pressure within the process chamber and changes the flow of plasma within the chamber. The need for an alteration in fluid flow is determined by using a plurality of pressure manometers 18 [[16]] within the plasma processing system 10 located, for example, about a periphery of the plasma processing device 10. When the pressure manometers 18 [[16]] detect a non-uniform flow or a flow that is outside a target range, the lift pins are actuated to adjust the flow.